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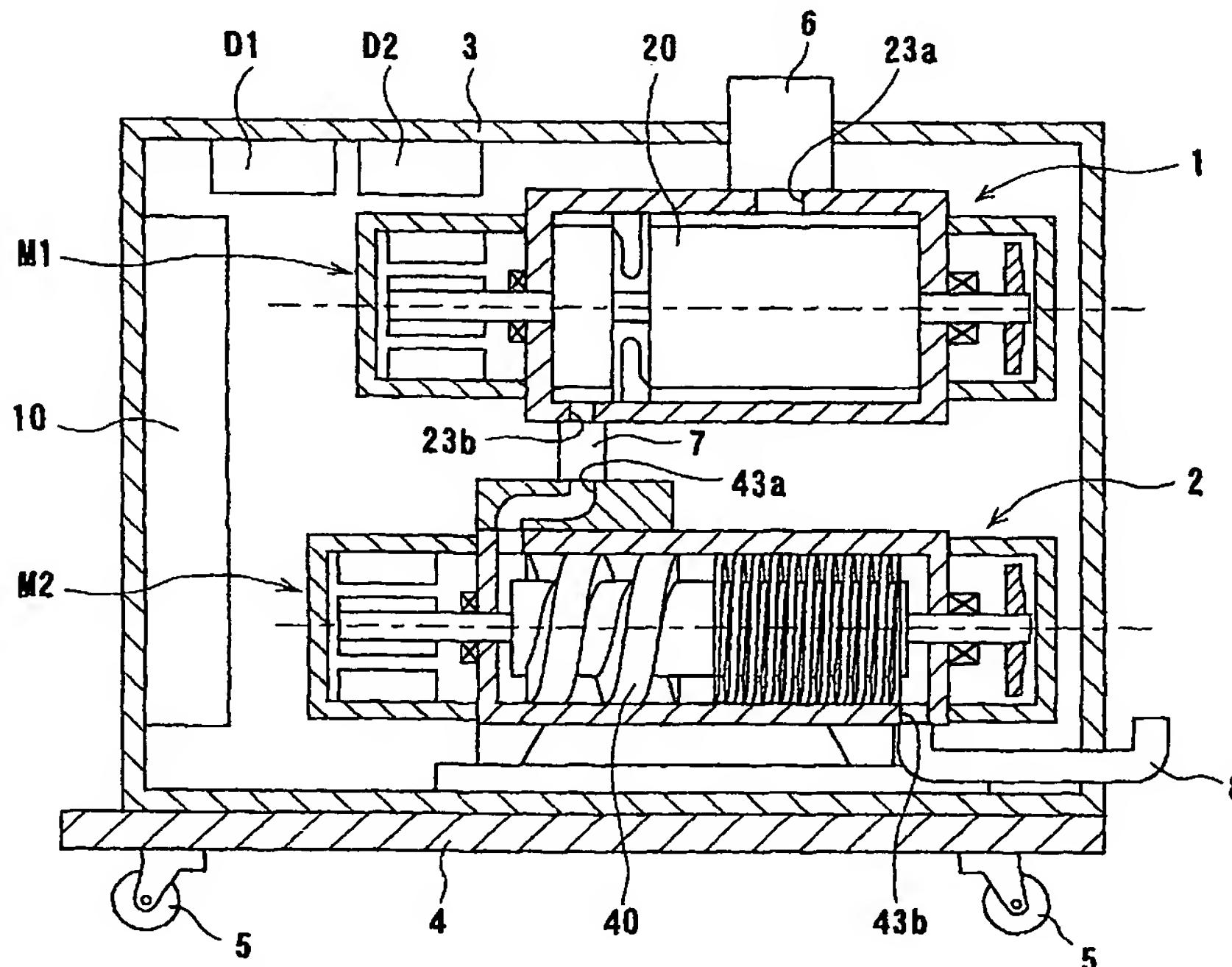
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[Continued on next page]

(54) Title: EVACUATION APPARATUS



(57) Abstract: The present invention relates to an evacuation apparatus for evacuating a vacuum chamber of a substrate processing apparatus for processing a substrate such as a semiconductor wafer or liquid crystal panel. An evacuation apparatus according to the present invention includes a first vacuum pump connected to a vacuum chamber, and a second vacuum pump connected to the first vacuum pump. The first vacuum pump has a pair of multistage pump rotors.

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